

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

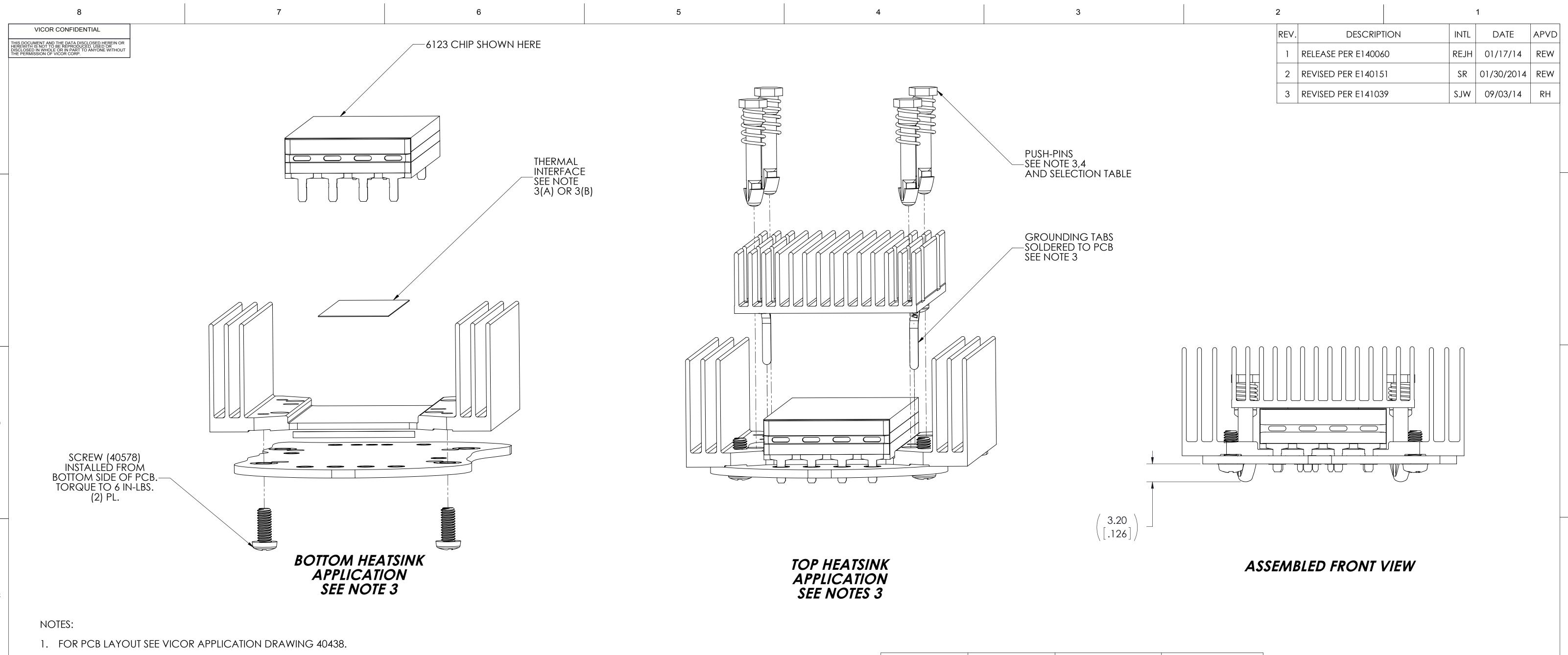
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









- 2. ROHS COMPLIANT PER CST-0001 LATEST REVISION.
- 3. THE SOLDERING METHOD USED FOR CHIPS (AND OPTIONAL HEATSINK GROUNDING) IS IMPORTANT WHEN SELECTING A THERMAL INTERFACE MATERIAL (TIM). THE PHASE-CHANGE TIM SHOWN IN THESE ILLUSTRATIONS MAY BE DAMAGED BY TEMPERATURES OVER 125C, SO TWO ASSEMBLY PROCEDURES ARE DESCRIBED BELOW: (A) FOR HAND-SOLDERING ONLY, (B) FOR WAVE-SOLDERING AND/OR HAND-SOLDERING.
- (A) PLACE BOTTOM-SIDE HEATSINK (WITH PRE-ATTACHED PHASE-CHANGE TIM) ON PCB. PLACE CHIP AND TOP-SIDE HEATSINK (WITH PRE-ATTACHED TIM AND GROUNDING TABS). WHILE SUPPORTING PCB, INSERT PLASTIC PUSH-PINS THROUGH BOTH HEATSINKS AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.)
 IMPORTANT: TO SET FINAL THICKNESS OF PHASE-CHANGE TIM ENSURE THAT THE ENTIRE ASSEMBLY IS RAISED ABOVE 65C FOR SEVERAL MINUTES.
 HAND-SOLDER ALL CHIP AND GROUNDING PINS. ADDITIONAL SOLDERING IRON HEAT MAY BE REQUIRED TO COMPENSATE FOR LOSSES TO THE HEATSINKS.
- (B) WAVE SOLDERING TEMPERATURES ARE UNSUITABLE FOR PLASTIC PUSH-PINS AND PHASE-CHANGE TIM, SO VICOR TIM 40325 (PARKER CHOMERICS GEL8010) IS RECOMMENDED. APPLY A UNIFORM .003" (.076MM) LAYER OF TIM 40325 TO THE TOP AND BOTTOM SURFACE OF THE CHIP, OR TO THE CORRESPONDING HEATSINK SURFACES. PLACE BOTTOM-SIDE HEATSINK, CHIP, AND TOP-SIDE HEATSINK ON PCB. WITH A CUSTOM FIXTURE APPLY APPROX. 10 LBS LOAD TO THE TOP-SIDE HEATSINK AND THEN WAVE-SOLDER ALL PINS. REMOVE FIXTURE AND INSERT PLASTIC PUSH-PINS THROUGH BOTH HEATSINKS AND PCB. (SELECT PROPER PUSH-PIN LENGTH FROM TABLE ON THIS DRAWING.)
- 4. CARE SHOULD BE TAKEN TO AVOID FULLY COMPRESSING THE PUSH-PIN SPRING DURING INSTALLATION AS THIS WOULD EXPOSE THE CHIP TO FORCES GREATER THAN THE RECOMMENDED LIMIT OF 3.1 LBF (13.8 N) PER PUSH-PIN.

	HEATSINK TYPE	P/N ASSY HEATSINKS, TIM AND GROUND TAB	P/N ASSY HEATSINK W/GROUND TAB ONLY
SOLDERING METHOD (SEE NOTE 2)	-	2(A) HAND SOLDER ONLY	2(B) WITH VICOR 40325 THERMAL GEL
4623	DUAL 11MM	40519	40527
4023	DUAL 19MM	40408	-
6123	DUAL 11MM	40520	40528
0123	DUAL 19MM	40409	-

HEATSINK OPTIONS

PUSH-PINS W/SPRINGS (100/BAG)	COLOR	PCB THK NOMINAL RANGE	PCB THK MINIMUM	PCB THK MAXIMUM
32436	BLUE	1.143 MM TO 1.854 MM [.045"] TO [.073"]	1.041 MM [.041"]	2.057 MM [.081"]
32437	GRAY	1.880 MM TO 2.438 MM [.074"] TO [.096"]	1.676 MM [.066"]	2.692 MM [.106"]

PUSH-PIN SELECTION

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	<u> </u>				7/12/2013	Robert Wasik
NK.	G, DUAL HEATSIN	VG. D	PP DI	A		UNLESS OTHERW DIMENSIONS ARE
· ,	6123, 4623	•			ANGLES .25] ±1°	TOLERANCES ADECIMALS $(X,XX) = \pm 0.01 = \pm 0.00$ $(X,XXX) = \pm 0.00$
		SE DIA(O.)	CAGE CO	SIZE	ROJECTION	THIRD ANGLE P
REV	DWG NO	DE DWG r		_		
REV 3	DWG NO 40191		6713	D		<u> </u>

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